## **Product / Process Change Notification**



#### N° 2018-100-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

# Implementation of 200mm wafer diameter in Villach and Kulim & introduction of an additional mold compound for 1200V IGBT4/EC4 products in TO247 package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 27. May 2019.
- Infineon aligns with the widely-recognized JEDEC STANDARD"JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Eckart Sünner Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck Registered Office: Neubiberg Commercial Register Amtsgericht München HRB 126492

## **Product / Process Change Notification**



#### N° 2018-100-A

Products affected: Please refer to attached affected product list 1\_cip18100\_a

### Detailed Change Information:

| Subject:                  | Implementation of 200mm wafer diameter in Villach and Kulim.<br>Introduction of an additional mold compound for products in TO247<br>package.          |  |
|---------------------------|--|--|
| Reason:                   | Capacity extension and implementation of 2 <sup>nd</sup> source.   |  |
| Description:              | <u>Old</u>   | New  |
| Wafer production location | Infineon Technologies Austria<br>AG, Villach   | Infineon Technologies (Kulim) Sdn.<br>Bhd, Kulim, Malaysia |
|                           |  | or   |
|                           |  | Infineon Technologies Austria AG,<br>Villach               |
| Wafer diameter            | 150mm  | 150mm  |
|                           |  | or   |
|                           |  | 200mm  |
| Mold compound             | Sumitomo EME E500 HA   | Sumitomo EME E500 HA                                       |
|                           |  | or   |
|                           |  | Kyocera KE G300 BH   |
|                           |  |  |
| Product Identification:   | Internal traceability assured via lot code and development code.<br>External traceability:<br>Sales code / SP number/ Product Barcode Label / Lot code |  |
|                           |  |  |
| Impact of Change:         | No impact on parameters and reliability as proven via product qualification.   |  |
| Attachments:              | Affected product list 1_cip18100_a<br>Qualification report 2_cip18100_a  | Q  |

## Product / Process Change Notification





#### ► Time Schedule:

- Final qualification report: Available (refer to attachment 2\_cip18100\_a)
  - First samples available: On request
- Intended start of delivery: 2019-07-15 or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.